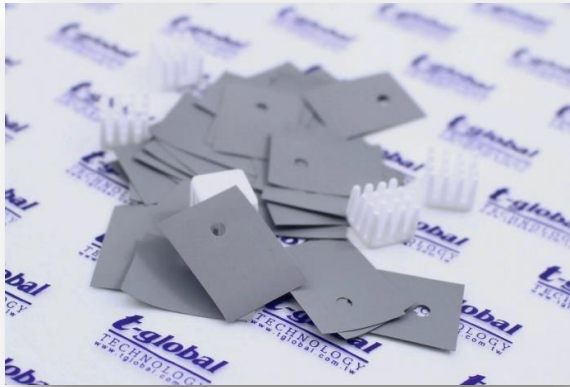


Ti900

Thermal Insulator



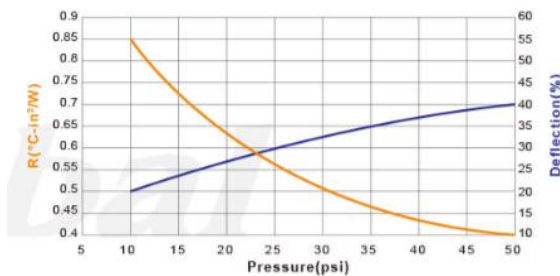
Features

- Insulation strength
- Low thermal resistance 0.402 (K in²/W) @ 50psi
- Easy to assemble

Applications

- Electronic components: IC, CPU, MOS, LED,
- Mother Board, Power Supply, Heat Sink, LCD-TV,
- Notebook, PC, Telecom Device, Wireless Hub,
- DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R(°C - in ² /W)	Deflection(%)
10	0.85	20
30	0.51	33
50	0.40	40

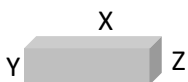
Properties ◆ REACH Compliant ◆ RoHS Compliant ◆ UL Compliant

Testing sample thickness: 0.12mm

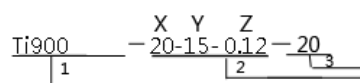
In "Thermal resistance V.S. Pressure V.S Deflection" chart, Ti900 provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage stays approximately the same.

Properties	Ti900	Unit	Tolerance	Test Method
Thermal Conductivity	1.8	W / mK	±0.18	ASTM D5470
Thickness	0.12	mm	-	ASTM D374
Color	Gray	-	-	Visual
Base	Polyimide	-	-	-
Insulation Strength Vac	6	KV	-	ASTM D149
Volume resistance	>10 ¹²	Ohm-m	-	ASTM D257
Working temperature	-50~+180	°C	-	-
Tensile Strength	5000	psi	-	ASTM D412
Elongation	40	%	-	ASTM D412
Flame rating UL	V-0	-	-	UL 94
Standard Shape	Sheet ones	-	-	-

Need samples?



Pre-cut for different shapes



1. Choose the P/N
2. Fill into size:x.y.z
3. Fill the quantity you need

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader

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